

# SEMICONDUCTOR TECHNICAL DATA



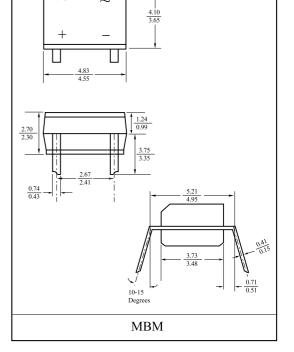
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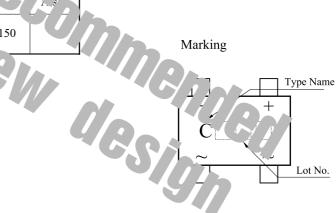
#### FEATURES

- Plastic package has Underwriters Laboratory flammability Classification 94V-0.
- · Glass passivated chip junction.
- High surge overload rating : 35A peak.
- $\cdot$  Saves space on printed circuit boards.
- $\cdot$  Recommended for non-automotive applications.

### MAXIMUM RATING (Ta=25)

CHARACTERISTIC	SYMBOL	RATING	UNIT
repetitive peak reverse voltage	V <sub>RRM</sub>	600	V
RMS voltage	V <sub>RMS</sub>	420	V
DC blocking voltage	V <sub>DC</sub>	600	V
Average forward output rectified current (see Fig.1) On glass-epoxy P.C.B on aluminum substrate.		0.5 (Note1) 0.8 (Note2)	А
Peak forward surge current	I <sub>FSM</sub>	s.V	А
Rating for fusing (t<8.3ms)	I <sup>2</sup> t	5.	13
Operating Junction and Storage Temperature Range	, Tstg	-55~150	





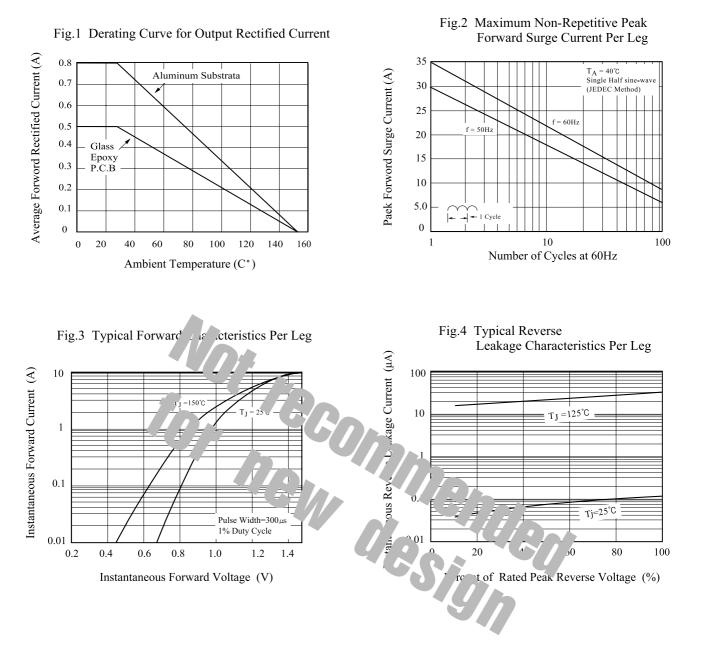
## ELECTRICAL CHARACTERISTICS (Ta=25)

CHARACTERIST	IC	SYMBOL	CONDITION	MIN	ТҮР	MAX	UNIT
Forward voltage		V <sub>F</sub>	I <sub>F</sub> =0.4A	-	-	1.0	V
Leakage current	Ta=25	I <sub>R</sub>	V <sub>R</sub> =600V	-	-	5.0	
	Ta=125	<sup>I</sup> R	v <sub>R</sub> =000 v	-	-	100	μA
Junction capacitance		CJ	V <sub>R</sub> =4.0V, f=1.0MHz	-	13	-	pF
Typical thermal resistance (		R <sub>th</sub> (A) (Note1)	Junction to ambient	-	-	85	/W
		R <sub>th</sub> (A) (Note 2)				70	
		R <sub>th</sub> (L) (Note 1)	Junction to lead	-	-	20	

Note 1) on glass epoxy P.C.B mounted on 0.05 × 0.05 "(1.3 × 1.3mm) Pads.

Note 2) on aluminum substrate P.C.B with an area of 0.8 × 0.8 '(20 × 20mm) mounted on 0.05 × 0.05 '(1.3 × 1.3mm) solder pad.

MB6M



#### Fig.5 Typical Junction Capacitance Per Leg

